IN THE CLAIMS

Claims 1-4, 6, 8-18 and 23-34 are pending in this application. Please cancel claims 5 and 7 without prejudice or disclaimer, amend claims 1-2 and 4, and add new claims 33-34 as follows:

1. (Currently Amended) A resin laminate sound insulation board which is a laminated plate, comprising:

a foamable resin ~~foamed at a foaming temperature by heating~~ in a substantially unfoamed state, the forabable resin being capable of changing the substantially unfoamed state to a foamed state by heating at a foaming temperature;

a shape-formable hard metal plate; and

a non-foamable material laminated between said foamable resin and said hard plate,

wherein said foamable resin and said non-foamable material are adhered to each other and said non-foamable material are adhered to said hard plate ~~prior to heating and prior to said hard plate being formed to a desired shape~~,

wherein the foamable resin in the substantially unfoamed state has a first thickness so as to allow the resin laminate sound insulation board to be shapable,

and

wherein the foamable resin is configured to have a second thickness in the foamed state so as to enhance rigidity of at least the hard metal plate.

~~said foamable resin is heated to a foamed state having a thickness that enhances a rigidity of at least said shaped hard plate.~~

2. (Currently Amended) A resin laminate sound insulation board which is a laminated plate, comprising:

at least a first foamable resin in a first substantially unfoamed state, the first foamable resin configured to be capable of changing the first substantially unfoamed state to a first foamed state by heating ~~foamed~~ at a first foaming temperature ~~by heating~~,

a second foamable resin in a second substantially unfoamed state, the second foamable resin configured to be capable of changing the second substantially unfoamed state to a second foamed state by heating ~~foamed~~ at a second foaming temperature ~~by heating~~,; and

a shape-formable hard metal plate,

wherein the first foamable resin is adhered to the hard plate and the second foamable resin is adhered to the first foamable resin ~~prior to the hard plate being formed to a desired shape~~,

wherein the first foamable resin in the first substantially unfoamed state and the second foamable resin in the second substantially unfoamed state have a first thickness in total so as to allow the resin laminate sound insulation board to be shapable, and

wherein at least one of said first foamable resin and said second foamable resins is configured to be in at least one of the first foamed state and the second foamed state and have a second thickness in total so as to enhance rigidity of at least the hard metal plate.

~~heated to a foamed state having a thickness that enhances a rigidity of at least said shaped hard plate~~.

3. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein the first foaming temperature of the first foamable resin is different from the second foaming temperature of the second foamable resin.

4. (Currently Amended) The resin laminate sound insulation board according to claim 2, wherein the melting point of the first ~~formable~~ foamable resin is different from that of the second foamable resin.

5. (Canceled).

6. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein the non-foamable material is a non-foamable resin not foamable by heating.

7. (Canceled)

8. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is heated at a temperature lower than the foaming temperature, and thermally fused to the hard plate to form the laminated plate.

9. (Previously Presented) The resin laminate sound insulation board according to claim 6, wherein said non-foamable resin is heated at a temperature lower than said foaming temperature, and thermally fused to the foamable resin to form the laminated plate.

10. (Previously Presented) The resin laminate sound insulation board according to claim 6, wherein a melting point of said non-foamable resin is higher than a melting point of said foamable resin.

11. (Previously Presented) The resin laminate sound insulation board according to claim 6, wherein said non-foamable resin is a thermosetting resin or a thermoplastic resin.

12. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is a thermosetting resin or a thermoplastic resin.

13. (Previously Presented) The resin laminate sound insulation board according to claim 11, wherein a melting point of said thermoplastic resin is 100-260° C.

14. (Previously Presented) The resin laminate sound insulation board according to claim 12 wherein a melting point of said thermoplastic resin is 100-260° C.

15. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is formed from a mixture of a foaming agent that is decomposable by heating with a resin.

16. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foaming temperature is set to 120-300° C.

17. (Previously Presented) A resin laminate sound insulation board according to claim 1, wherein the foamed resin laminate sound insulation board according is heated to said foaming temperature to make the foamable resin into a foamed resin.

18. (Previously Presented) The resin laminate sound insulation board according to claim 17, wherein said foamable resin is made into the foamed resin by heating after the foamed resin laminate sound insulation board is worked into a prescribed shape.

19. (Withdrawn) A method for manufacturing a foamed resin laminate sound insulation board comprising: a laminating process for laminating at least an unfoamed foamable resin to be foamed at a foaming temperature by heating and a hard plate; and a process for integrating the laminate of said foamable resin and the hard plate at a temperature lower than the foaming temperature of the foamable resin.

20. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 19 comprising the laminating process, said laminate integrating process, and a heating process for heating the laminate to the foaming temperature of said foamable resin to make said foamable resin to a foamed resin.

21. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 20 comprising said laminating process, the laminate integrating process, a molding process for working the laminate into a prescribed shape in the integrated state, and said heating process.

22. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 20 wherein said heating process is carried out simultaneously with a heating treatment for baking finish.

23. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein at least one of said first and second foamable resins is heated at a temperature lower than the corresponding first or second foaming temperature, and thermally fused to the hard plate or first foamable resin, respectively.

24. (Previously Presented) The resin laminate sound insulation board according to claim 7, wherein said non-foamable resin is heated at a temperature lower than said foaming temperature, and thermally fused to the hard plate.

25. (Previously Presented) The resin laminate sound insulation board according to claim 7, wherein the melting point of said non-foamable resin is higher than the melting point of said foamable resin.

26. (Previously Presented) The resin laminate sound insulation board according to claim 7, wherein said non-foamable resin is a thermosetting resin or a thermoplastic resin.

27. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein said foamable resin is a thermosetting resin or a thermoplastic resin.

28. (Previously Presented) The resin laminate sound insulation board according to claim 26, wherein a melting point of said thermoplastic resin is 100-260° C.

29. (Previously Presented) The resin laminate sound insulation board according to claim 27, wherein a melting point of said thermoplastic resin is 100-260° C.

30. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein said foamable resin is formed from a mixture of a foaming agent that is decomposable by heating with a resin.

31. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein said foaming temperature is set to 120-300° C.

32. (Previously Presented) A resin laminate sound insulation board according to claim 2, wherein the foamed resin laminate sound insulation board is heated to said foaming temperature to make the foamable resin into a foamed resin.

33. (New) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is configured to have a shape having a first surface and a second surface in the foamed state, the second surface is opposite to the first surface and contacts the non-foamable material, and the first surface has a shape corresponding to the desired shape.

34. (New) The resin laminate sound insulation board according to claim 2, wherein said second foamable resin is configured to have a shape having a first surface and a second surface in the foamed state, the second surface is opposite to the first surface and contacts the first foamable resin, and the first surface has a shape corresponding to the desired shape.